

Fastboot Table

User Guide

Issue 02

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About This Document

Purpose

This document describes how to use and configure the fastboot table. It applies to the HiSilicon Linux software development kit (SDK) and Android SDK.

Related Versions

The following table lists the product versions related to this document.

Product Name	Version
Hi3796C	V1XX
Hi3798C	V1XX
Hi3798M	V1XX
Hi3796M	V1XX
Hi3798C	V2XX

Intended Audience

This document is intended for:

- Technical support personnel
- Software development engineers

Change History

Changes between document issues are cumulative. Therefore, the latest document issue contains all changes made in previous issues.

Issue 02 (2015-05-20)

This issue is the second official release, which incorporates the following changes:



Hi3798C V2XX is supported.

Chapter 6 Modification Instances

Section 6.1.3 is added, and section 6.2.1 is modified.

Issue 01 (2014-10-30)

This issue is the first official release, which incorporates the following change: Hi3796M V100 is supported.

Issue 00B02 (2014-08-19)

This issue is the second draft release.

Issue 00B01 (2014-06-20)

This issue is the first draft release.



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1 Usage

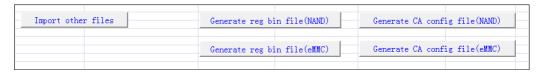


CAUTION

For details about the naming conventions, applicable boards, and intended customers of the fastboot table, see **readme_*** in the document contents of the fastboot table contained in the SDK.

The fastboot table describes register configurations. Several buttons are available in the **main** sheet, as shown in Figure 1-1.

Figure 1-1 main sheet



The button functions are described as follows:

Import other files

Imports contents from other tables. (This button is applicable only to R&D personnel.)

• Generate reg bin file(NAND)

Generates the register configuration file *_nand.reg in the SDK for the non-CA board with the NAND flash. This file is compiled to the boot during compilation.

• Generate reg bin file(eMMC)

Generates the board register configuration file *_emmc.reg in the SDK for the non-CA board with the eMMC. This file is compiled to the boot during compilation.

• Generate CA config file(NAND)

Generates the configuration file used by CA boot for the CA board with the NAND flash.

• Generate CA config file(eMMC)

Generates the configuration file used by CA boot for the CA board with the eMMC.



2 Content

The fastboot table contains register configurations, including key parameters of board hardware, phase-locked loop (PLL), double data rate (DDR), peripheral clock, pin multiplexing, and Ethernet port configurations. The fastboot table is divided into two parts: ITEM 1 and ITEM 2. Basic parameters are set in ITEM 1. ITEM 2 are reserved at present, but cannot be deleted.

The fastboot table consists of multiple sheets. Generally, one module or one mode is configured in one sheet. However, the DDR is configured in multiple sheets. The registers of each module are configured based on the system startup sequence, and the sheets are arranged by priority. You are advised not to change the sheet configuration sequence. The sheets are described as follows:

main

Provides command buttons and version upgrade records. You can fill in version information based on product requirements.

hardware_key_info

Describes key hardware information, including the dominant frequency of the CPU and DDR, basic DDR information, dynamic voltage and frequency scaling (DVFS) channel selection, basic Ethernet port information, and system driver configurations. Information in this sheet is only for reference, and you do not need to modify the information.

sys_clk

Sets the system clock ratio, other clock parameters, and CPU mode, and displays the clock frequency of the CPU and DDR. You are prohibited from modifying the information in this sheet.

sysctrl noCA

Sets system control for the non-CA boards. Do not modify the information (except pin multiplexing) in this sheet. Otherwise, the system may fail.

• sysctrl_CA (optional)

Sets system control for the CA boards. Do not modify the information (except pin multiplexing of the front panel) in this sheet. Otherwise, the system may fail.

Note that **sysctrl_noCA** or **sysctrl_CA** is compiled to generate the image based on whether the board is a non-CA board or a CA board. If pin multiplexing of the front panel needs to be modified, you are advised to modify both sheets.

• mddrc, ddrphy, ddr_poweron, and ddr_wakeup



Sets DDR initialization, including DDR controller and DDR PHY settings. Do not modify the information in this sheet. Otherwise, the system may fail.

qos ctrl

Sets the priorities of system modules and peripheral modules. Do not modify the information in this sheet. Otherwise, the system may fail.

crg_ctrl

Controls clock gating and resetting for each module. The clock of each module is disabled by default. Do not modify the information in this sheet. Otherwise, the system may fail.

clk_ssmod

Sets the spread spectrum for each PPL. The spread spectrums of all PLLs are disabled by default. Do not modify the information in this sheet. Otherwise, the system may fail.

peri_cfg

Manages the power consumption of peripheral modules. The USB, VDAC, and ADAC modules are in the Power down state by default. Do not modify the information in this sheet. Otherwise, the system may fail.

• pin_mux_drv_emmc

Configures pin multiplexing and drive capability for boards with the eMMC. Pin multiplexing is determined by specific application scenarios, and drive capability is determined by PCB layers. You can modify the information in this sheet based on the *Hi379X VXXX Hardware User Guide*.

• pin_mux_drv_nand

Configures pin multiplexing and drive capability for boards with the NAND flash. Pin multiplexing is determined by specific application scenarios, and drive capability is determined by PCB layers. You can modify the information in this sheet based on the *Hi379X VXXX Hardware User Guide*.

Note that **pin_mux_drv_emmc** or **pin_mux_drv_nand** is compiled to generate the image based on whether the flash memory is the NAND flash or eMMC. If pin multiplexing needs to be modified, you are advised to modify both sheets (the difference between the two sheets lies only in the eMMC or NAND flash configuration part).

eth_phy_cfg

Sets Ethernet ports, including settings of the MAC channels, MAC port types, PHY addresses, MDC/MDIO control (not for Hi3798M V100), and external PHY reset signals (not for Hi3798M V100). You can modify the information in this sheet based on product requirements.

others

Describes ITEM 2 (reserved at present).



3 Function Description

3.1 Overview

This section describes a sheet of the fastboot table, as shown in Figure 3-1.

Figure 3-1 Configuring peripherals

Module Name	mddrc	MDDRC Initialize					
Base Address	0xf8a31000			. 1			1
ITEM1/2	1		Add mods	Пe		Ad	d register
Priority	3						
Execution Required for Standby Wakeup	Υ						
Execution Required for Normal Boot	Y						
Register	Offset Address	Value Written to or Read from Register	delay	Read or Write	Read or	Start Bit to Be Read or Written	Register Attribute
DDRC_CFG_INIT	0x24	0x8	0	write	31	0	0x0000000FF
DDRC_CFG_AREF	0x2c	0x0	0	write	31	0	0x0000000FF
DDRC_CFG_WORKMODE	0x40	0x11002001	0	write	31	0	0x0000000FF
DDRC_CFG_DDRMODE	0x50	0x26	0	write	31	0	0x0000000FF
DDRC_CFG_RNKVOL	0x60	0x152	0	write	31	0	0x0000000FF
DDRC_CFG_EMRS01	0x70	0x61 f70	0	write	31	0	0x0000000FF
DDRC_CFG_EMRS23	0x74	0x18	0	write	31	0	0x0000000FF
DDRC_CFG_TIMINGO	0x80	0x4639d610	0	write	31	0	0x0000000FF
DDRC_CFG_TIMING1	0x84	0x3f38b080	0	write	31	0	0x0000000FF
DDRC_CFG_TIMING2	0x88	0x44016000	0	write	31	0	0x0000000FF
DDRC_CFG_TIMING3	0x8c	0xffd1f784	0	write	31	0	0x0000000FF
DDRC_CFG_TIMING4	0x90	0x820f18	0	write	31	0	0x0000000FF
DDRC_CFG_TIMING5	0x94	0x2707	0	write	31	0	0x0000000FF
DDRC_CFG_ODT	0xc0	0x1	0	write	31	0	0x0000000FF
DDRC_CFG_DMCLVL	0xc4	Оже	0	write	31	0	0x0000000FF
DDRC_CFG_DDRPHY	0x200	0x1000	0	write	31	0	0x0000000FF
DDRC_CFG_SREF	0x20	0x8101	0	write	31	0	0x0000000FF

Items in the sheet shown in Figure 3-1 are described as follows:

- Two buttons
 - Add module: Clicking this button adds a sheet on the right of the current sheet.
 - Add register: Clicking this button adds a row under the current row.
- Module Name

Indicates the usage of this sheet and the module to be configured. Generally, **Module Name** is the same as the name of the current sheet.

Base Address



Indicates the base address for registers. In this sheet, only the offset address for each register is provided. The actual address for each register is the value specified in **Base Address** plus the corresponding offset address.

Priority

Specifies the configuration sequence. The priority of each sheet is unique and is numbered from 0.

• Execution Required for Standby Wakeup

Indicates whether the configurations in the current sheet are required when the system wakes up from the standby mode.

- Y: required
- N: not required

Execution Required for Normal Boot

Indicates whether the configurations in the current sheet are required when the system is powered on.

Register

Indicates the register name, for facilitating maintenance.

Offset Address

Indicates the offset address for each register relative to the base address.

Value Written to or Read from Register

Indicates the value to be written or read for comparison.

delay

Indicates the delay time after a register is configured.

• Read or Write

Specifies the write or read operation.

• Bits to Be Read or Written

Indicates the number of bits to be read or written. The value is the number of actual bits to be read or written minus 1. For example, if 32 bits need to be written, the value is 31; if one bit needs to be written, the value is 0.

Start Bit to Be Read or Written

Indicates the start bit to be read or written. For example, if you want to write data from bit 0, the value is **0**, and so on.

Register Attribute

Indicates the register attribute. The contents in this column are automatically generated and can be ignored.

3.2 Pin Multiplexing and Drive Capability

For the Hi3798C/Hi3796C, the valid contents of pin multiplexing registers include pin multiplexing (bit[3:0]) and drive capabilities (bit[7:4]), which are configured in different registers. Registers in the upper part of the **pin_mux_drv_nand** and **pin_mux_drv_emmc** sheets are used for configuring pin multiplexing, and those in the lower part are used for configuring drive capabilities. See Figure 3-2.



Figure 3-2 pin_mux_drv (for the Hi3798C/Hi3796C)

										i company and a second a second and a second a second and	
demo_gpioO	0x0000019C	0x00000002	0	write	7	0	0x0000003F		GPI014_0	AT41	
demo_gpio1	0x000001A0	0x00000002	0	write	7	0	0x0000003F		GPI014_1	AR39	
demo_gpio3	0x000001A8	0x00000002	0	write	7	0	0x0000003F		GPI014_3	AW39	
demo_gpio4	0x000001AC	0x00000002	0	write	7	0	0x0000003F		GPI014_4	AY40	
demo_gpio5	0x000001B0	0x00000002	0	write	7	0	0x0000003F		GPI014_5	AR40	
demo_gpio6	0x000001B4	0x00000002	0	write	7	0	0x0000003F		GPI014_6	AR38	
i2s0_gpio47	0x000001B8	0x00000002	0	write	7	0	0x0000003F		GPI014_7	AW2	
i2s0_gpio97	0x000001BC	0x00000002	0	write	7	0	0x0000003F	GPIO	GPI09_7	AY3	
i2s0_gpio100	0x000001C0	0x00000002	0	write	7	0	0x0000003F	GFIO	GPI010_0	AY4	
i2s0_bootsel1	0x000001C4	0x00000003	0	write	7	0	0x0000003F		GPI010_1	BA4	
i2s0_gpio35	0x000001CC	0x00000002	0	write	7	0	0x0000003F		GPI013_5	AY5	
i2s1_gpio27	0x000001D8	0x00000002	0	write	7	0	0x0000003F		GPI012_7	C28	
i2s1_gpio30	0x000001DC	0x00000002	0	write	7	0	0x0000003F		GPI013_0	A29	
i2s1_bootsel0	0x000001E0	0x00000002	0	write	7	0	0x0000003F		GPI013_1	A28	
i2c0_gpio32	0x000001E4	0x00000002	0	write	7	0	0x0000003F		GPI013_2	D28	
i2c0_gpio33	0x000001E8	0x00000002	0	write	7	0	0x0000003F		GPI013_3	B28	
sfc_dio_ctrl	0x00000800	0x000000a0	0	write	7	0	0x0000003F		SFC_DIO	FAST	10
sfc_wpn_ctrl	0x00000804	0x000000a0	0	write	7	0	0x0000003F		SFC_WPN_IO2	FAST	10
sfc_clk_ctrl	0x00000808	0x000000a0	0	write	7	0	0x0000003F	CDI data afa	SFC_CLK	FAST	10
sfc_doi_ctrl	0x0000080C	0x000000a0	0	write	7	0	0x0000003F	SPI drive cfg	SFC_DOI	FAST	10
sfc_holdn_ctrl	0x00000810	0x000000a0	0	write	7	0	0x0000003F		SFC_HOLDN_IO3	FAST	10
sfc_csin_ctrl	0x00000814	0х000000ъ0	0	write	7	0	0x0000003F		SFC_CS1N	FAST	11

For the Hi3798M, the valid contents of pin multiplexing registers include pin multiplexing (bit[7:0]) and drive capabilities (bit[11:8]), which are configured in different registers. **pin_mux_drv_nand** and **pin_mux_drv_emmc** list the pin multiplexing and drive capability configuration registers. See Figure 3-3.



Figure 3-3 pin_mux_drv (for the Hi3798M)

Register	Offset Address	Value Written to or Read from Register	delay	Read or Write	Bits to Be Read or Written	Start Bit to Be Read or Written	Register Attribute
ioshare_O	0x0	0x1f01	0	write	11	0	0x0000005F
ioshare_1	0x4	0xf01	0	write	11	0	0x0000005F
ioshare_2	0x8	0xf01	0	write	11	0	0x0000005F
ioshare_3	0xc	0xf01	0	write	11	0	0x0000005F
ioshare_4	0x10	0xf01	0	write	11	0	0x0000005F
ioshare_5	0x14	0xf01	0	write	11	0	0x0000005F
ioshare_6	0x18	0xf01	0	write	11	0	0x0000005F
ioshare 7	0x1c	0xf01	0	write	11	0	0x0000005F
ioshare_8	0x20	0x701	0	write	11	0	0x0000005F
ioshare 9	0x24	0x701	0	write	11	0	0x0000005F
ioshare_10	0x28	0x701	0	write	11	0	0x0000005F
ioshare 11	0x2c	0xf01	0	write	11	0	0x0000005F
ioshare_12	0x30	0x d01	0	write	11	0	0x0000005F
ioshare_13	0x34	0x701	0	write	11	0	0x0000005F
ioshare_21	0x54	0x700	0	write	11	0	0x0000005F
ioshare 22	0x58	0x700	0	write	11	0	0x0000005F
ioshare_23	0x5c	0xf00	0	write	11	0	0x0000005F
ioshare_24	0x60	0x500	0	write	11	0	0x0000005F
ioshare 25	0x64	0x300	0	write	11	0	0x0000005F
ioshare_31	0x7c	0xf00	0	write	11	0	0x0000005F
ioshare_32	0x80	0xf00	0	write	11	0	0x0000005F
ioshare_43	Oxac	0xf01	0	write	11	0	0x0000005F
ioshare 44	0xb0	0xf00	0	write	11	0	0x0000005F
ioshare_45	0xb4	0x1	0	write	7	0	0x0000003F
ioshare_46	0xb8	0x1	0	write	7	0	0x0000003F
ioshare_47	0xbc	0x1	0	write	7	0	0x0000003F
ioshare_48	0xc0	0x1	0	write	7	0	0x0000003F
ioshare_54	0xd8	0xf01	0	write	11	0	0x0000005F
ioshare_55	Oxde	0xf01	0	write	11	0	0x0000005F
ioshare_56	0xe0	0x701	0	write	11	0	0x0000005F
ioshare_57	Oxe4	0x701	0	write	11	0	0x0000005F
ioshare_58	Oxe8	0x701	0	write	11	0	0x0000005F
ioshare_59	Oxec	0x501	0	write	11	0	0x0000005F
ioshare_60	0xf0	0x701	0	write	11	0	0x0000005F
ioshare_61	0xf4	0x701	0	write	11	0	0x0000005F
ioshare_62	0xf8	0x701	0	write	11	0	0x0000005F
ioshare_63	Oxfc	0x701	0	write	11	0	0x0000005F
ioshare_64	0x100	0x701	0	write	11	0	0x0000005F

- For I/O with fixed drive capability, only pin multiplexing is available (determined by the specified application scenarios). In the fastboot table, set **Start Bit to Be Read or Written** to **0** and **Bits to Be Read or Written** to **7** for bit[7:0]. A total of 8 bits are set.
- For I/O with adjustable drive capability, pin multiplexing and drive capability are available. The drive capability must be set based on the PCB layers. In the fastboot table, set **Start Bit to Be Read or Written** to **0** and **Bits to Be Read or Written** to **11** for bit[11:0]. A total of 12 bits are set.

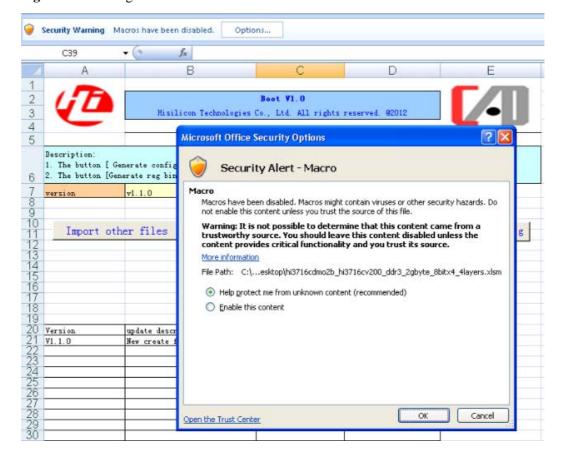


4 Precautions

Take the following precautions before you use or modify the fastboot table:

• Table usage
Enable macros before you click any button in the fastboot table, as shown in Figure 4-1.

Figure 4-1 Enabling macros



• Table modification

Generally, you need to modify only pin multiplexing, drive capability, and Ethernet port configurations in pin_mux_drv_nand/pin_mux_drv_emmc and eth_phy_cfg of the



fastboot table based on the hardware connections and PCB layers of products. Do not modify other information. Otherwise, the system may fail. If a customer requests to modify other information, contact HiSilicon FAEs.

- Ensure that the priorities of sheets are consecutive, each sheet name is the same as the value specified in **Module Name**, and no blank row is left in each sheet.
- Add or modify the information in the fastboot table by using macros.



5 Operation Procedure

To compile a boot, perform the following steps:

Step 1 Generate the **x.reg** file.

Open the boot table corresponding to the used board.

In the main sheet, click Generate reg bin file(NAND) or Generate reg bin file(eMMC). The x.reg file is generated in the current directory.

Step 2 Compile the file.

- Linux
 - Store the generated **x.reg** file to **\${LINUX_SDK}/source/boot/sysreg/**. (Skip this step if the file is generated in this directory.)
 - Run make hiboot_clean;make hiboot_install in the \${LINUX_SDK} directory to compile the file.
 - After compilation, the fastboot-burn.bin file is generated in \${LINUX_SDK}/pub/image. Burn the file directly.
- Android
 - Store the generated x.reg file to \${ANDROID_SDK}/device/hisilicon/bigfish/sdk/source/boot/sysreg/. (Skip this step if the file is generated in this directory.)
 - Compile the file in the \${ANDROID_SDK} directory by running the following commands:

source build/envsetup.sh

lunch configuration

make hiboot

After compilation, the fastboot.bin file is generated in \${ ANDROID_SDK }/
out/target/product/\${configured product}/Emmc (or Nand)/. Burn the file directly.

----End



6 Modification Instances

6.1 Configuring Ethernet Ports

6.1.1 Hi3798C V100/Hi3796C V100

This section describes how to configure Ethernet ports for the Hi3798C V100. The Hi3798C V100 provides two internal MAC modules and supports two Ethernet ports at a time, for example:

- One external GE PHY port
- One external FE PHY port and one external GE PHY port

In the fastboot configuration table, configurations related to the Ethernet ports include the following:

- MAC port type. For MII0, MII, RMII, and RGMII can be selected; for MII1, only RMII
 can be selected. Hi3798C V100 uses the MII mode by default.
- PHY address corresponding to the MAC. The external PHY addresses must be consistent with the hardware.
- MDCK/MDIO of the PHY corresponding to the MAC (MDCK0/MDIO0 or MDCK1/MDIO1). Hi3798C V100 uses MDCK0/MDIO0 by default.
- External PHY reset pin GPIO. If the GPIO signal is used as the reset signal, the GPIO group ID and GPIO ID must be specified.
- Pin multiplexing and drive capability configuration, which are related to the chip interfaces and number of PCB layers

For example:

- Select the embedded GE PHY for MAC0.
- Select MDCK0/MDIO0 as the control signal.
- Select GPIO13_0 as the external GE PHY reset pin.
- Select the 4-layer PCB.
- Pin multiplexing is not configured, which is RGMII by default.

Figure 6-1 shows the corresponding Ethernet port configurations.



Figure 6-1 eth phy cfg

Module Name	eth_phy_cfg	eth_phy_cfg						
Base Address	0xf8000000							
ITEM1/2	1			Add module			Add register	
Priority	14							
Execution Required	v							
for Standby Wakeup	T							
Execution Required	v							
for Normal Boot	'							
Register	Offset Address	Value Written to or Read from Register	delay	Read or Write	Read or	Start Bit to Be Read or Written	Register Attribute	
MACO_IF	0x184300c	0x1	0	write	3	5	1 0.000002817	MACO Select MII Interface 5:7(000: GMII/MII mode; 001: RGMII mode; 100: RMII mode∘
MACO_PHY_ADDR	0xA8	0x1	0	write	7	0	0x0000003F	MACO_PHY_ADDR = 0x1, range[131]
MACO_PHY_CTRL	0xA8	0x0	0	write	7	8	0x0000403F	MACO_PHY_Select MDIOO/MDCK0; 0 or 1
MACO_PHY_RST_GPIO	0xAC	0×D	0	write	7	0	0x0000003F	MACO PHY RST GPIO Group Num, fill 0xFF if not used •
MACO_PHY_RST_GPIO_B IT	0xAC	0x0	0	write	7	8	0x0000403F	MACO PHY RST GPIO Bit Num, fill 0xFF if not used
MAC1_PHY_CTRL	0xA8	0x1	0	write	7	24	0x00000C03F	MAC1_PHY_Select MDIO1/MDCK1; 0 or 1

The configuration items on the **eth_phy_cfg** sheet are described as follows:

• Row 8

The MAC0 interface type is set to RGMII.

• Row 9

The address for the embedded GE PHY is set to 1.

Row 10

The GE PHY uses MDCK0/MDIO0 as the control signal.

• Rows 11 to 12

The reset GPIO pin of the PHY corresponding to MAC0 is not required, which is set to the reserved value **0xFF**.

• Row 13

MAC1 uses MDCK1/MDIO1 as the control signal.

6.1.2 Hi3798M V100

Hi3798M V100 has an embedded FE PHY and supports one Ethernet port.

In the fastboot configuration table, configurations related to the Ethernet ports include the following:

- PHY address corresponding to the MAC. The external PHY addresses must be consistent with the hardware (0x1 for Hi3798M V100).
- MDCK/MDIO of the PHY corresponding to the MAC (0x0 for Hi3798M V100)
- External PHY reset pin GPIO. If the GPIO signal is used as the reset signal, the GPIO group ID and GPIO ID must be specified (0xFF for Hi3798M V100).
- Pin multiplexing and drive capability configuration, which are related to the chip interfaces and number of PCB layers (not required for Hi3798M V100)

For example:

- Select the embedded GE PHY for MAC0.
- Select MDCK0/MDIO0 as the control signal.
- Select GPIO13 0 as the external GE PHY reset pin.
- Select the 4-layer PCB.



• Pin multiplexing is not configured, which is RGMII by default.

Figure 6-2 shows the corresponding Ethernet port configurations.

Figure 6-2 eth phy cfg

1	Module Name	int_fephy	when use internal feph	y				
2	Base Address	0xf0000000		Add module			844	register
3	ITEM1/2	2		Maa moaare			, Add	register
4	Priority	13						
5	Execution Required for Standby Wakeup	Y						
6	Execution Required for Normal Boot	Y						
7	Register	Offset Address	Value Written to or Read from Register	delay	Read or Write	Read or	Start Bit to Be Read or Written	Register Attribute
8	PERI_CTRL	0x8a20008	0x0	0	write	0	8	0x00004007
9	MACO_IF	0x984300c	0x0	0	write	2	5	0x00002817
10	PHY_CTRL_ADDR	0x80000A8	0x2	0	write	7	0	0x0000003F
11	PHY_CTRL_ADDR	0x80000A8	0x0	0	write	7	8	0x0000403F
12	MACO_PHY_RST_GPIO	0x80000AC	0xff	0	write	7	0	0x0000003F
13	MACO_PHY_RST_GPIO_BIT	0x80000AC	0xff	0	write	7	8	0x0000403F
14	PERI_CTRL	0x8a20008	0x0	0	write	0	9	0x00004807
15	MAC1_IF	0x9843010	0x1	0	write	2	5	0x00002817
16	PHY_CTRL_ADDR	0x80000A8	0x1	0	write	7	16	0x00000803F
17	PHY_CTRL_ADDR	0x80000A8	0x1	0	write	7	24	0x00000C03F
18	MAC1_PHY_RST_GPIO	0x80000AC	0x5	0	write	7	16	0x00000803F
19	MAC1_PHY_RST_GPIO_BIT	0x80000AC	0x1	0	write	7	24	0x00000C03F

The configuration items on the **eth_phy_cfg** sheet are described as follows:

Row 8

The address for the embedded FE PHY is set to 1.

• Row 9

The embedded FE PHY uses MDCK0/MDIO0 as the control signal.

• Rows 10 to 11

The reset GPIO pin of the PHY corresponding to the MAC is not required, which is set to the reserved value **0xFF**.

6.1.3 Hi3798C V200_A

Hi3798C V200_A has three MACs and can support three Ethernet ports at the same time:

- Three external GE PHYs/FE PHYs
- One external FE PHY+Two external GE PHYs/FE PHYs

In the fastboot configuration table, configurations related to the Ethernet ports include the following:

- MAC port type. For MAC0, MII, RMII, and RGMII can be selected; for MAC1 or MAC2, only RMII or RGMII can be selected. Hi3798C V200_A uses the RGMII mode by default.
- PHY address corresponding to the MAC. The external PHY addresses must be consistent with the hardware.
- MDCK/MDIO of the PHY corresponding to the MAC (MDCK0/MDIO0 or MDCK1/MDIO1)

MAC2 PHY RST GPIO Bit Num, fill 0xFF if not used



- External PHY reset pin GPIO. If the GPIO signal is used as the reset signal, the GPIO group ID and GPIO ID must be specified. If the default reset signal is used or the reset signal is not used, it is set to 0xFF.
- Pin multiplexing and drive capability configurations, which are related to the chip interfaces and number of PCB layers

For example:

- Select the embedded GE PHY for MAC0.
- Select MDCK1/MDIO1 as the control signal.
- Select the dedicated RESET pin as the external GE PHY reset pin.
- Select the 4-layer PCB.
- Pin multiplexing is not configured, which is RGMII by default.

Figure 6-3 shows the corresponding Ethernet port configurations.

eth_phy_cfg Module Name eth_phy_cfg 3 4 Base Address Add module Add register ITEM1/2 Priority Execution Required 5 for Standby Wakeup Execution Required 6 for Normal Boot Register Offset Address delay Read or Write Read or Be Read or Register Attribute Read from Register 8 PERI_FEPHY_LDO_CTRL; enable & vset = 4'h8 MACO Select GRMIIO (0:FE PHY/1:RGMIIO IO) PERI_FEPHY_LDO_CTRL 0xa20844 0x18 write PERI_CTRL write 0x00004001 10 11 12 13 14 15 16 MACO Select RGMII Interface (0-mii, 1-rgmii, 4-rmii) MACO_PHY_ADDR = 0x1, range[1-31] (FEPHY Addr = 0x2) MACO_PHY_Select MDIO1/MDCK1; 0 or 1 MACO IF 0x184300c write 0x00002817 write 0xA8 MACO_PHY_CTRL 0x1write 0x00004031 Ox AC MACO_PHY_RST_GPIO 0xff write write 0x0000003F MACO PHY RST GPIO Group Num, fill 0xFF if not used 0x0000403 0x0000281 MACO_PHY_RST_GPIO_BIT 0xff MACO PHY RST GPIO Bit Num. fill 0xFF if not used MAC1 Select RGMII Interface (0-mii, 1-rgmii, 4-rmii) MAC1_IF 0x1843010 0x1 write MAC1 PHY ADDR 0xA8 0x000008031 MAC1 PHY ADDR =0x3 17 18 19 20 MAC1_PHY_CTRL MAC1_PHY_RST_GPIO MAC1_PHY_Select MDIO1/MDCK1; 0 or 1 MAC1_PHY RST GPIO Group Num, fill 0xFF if not used 0xff write 0xff 0x1 MAC1_PHY_RST_GPIO_BIT OxAC 0x00000C03F MAC1 PHY RST GPIO Bit Num, fill 0xFF if not used write MAC2 select RGMII Interface MAC2_PHY_ADDR =0x7 MAC2_IF MAC2_PHY_ADDR 0xa222d 21 MAC2_PHY_ADDR
22 MAC2_PHY_RST_GPIO
23 MAC2_PHY_RST_GPIO_BIT write 0x0000003F 0xff 0x0000403F MAC2 PHY RST GPIO Group Num, fill 0xFF if not used

Figure 6-3 eth_phy_cfg

The configuration items on the **eth_phy_cfg** sheet are described as follows:

Row 9

The MAC0 interface type is set to the one that connects to the external PHY.

The MAC0 interface type is set to RGMII.

Row 11

The address for the embedded GE PHY is set to 1.

The GE PHY uses MDCK1/MDIO1 as the control signal.

Rows 13 to 14

The reserved value 0xFF is used if the reset GPIO of the PHY corresponding to MAC0 is not used. The dedicated external PHY reset pin is used by default.



6.2 Viewing the DDR Capacity

6.2.1 Hi3798C V100/Hi3796C V100/Hi3798C V200_A

Take Hi3798C V100 as an example. In hi3798cdmo1a_hi3798cv100_ddr3_16bit x4_4layers.xlsm, four 256 Mbits x 16 (totally 2 GB) DDR SDRAMs are used. Therefore, the DDRC registers with the addresses of 0x8060 and 0x9060 are set to 0x142. See Figure 6-4.

Figure 6-4 0x8060 and 0x9060 registers

	DDRC_CFG_RNKVOL	0x8060	0x142	0	write	31	0	0x0000000FF
ı	DDRC_CFG_RNKVOL	0x9060	0x142	0	write	31	0	0x0000000FF

Table 6-1 describes the mapping between the configured value and the capacity of a DDR.

Table 6-1 Mapping between the configured value and the capacity of a DDR

Capacity of a DDR	0x8060/0x9060 Register Configurations
128 Mbits x 16	0x132
256 Mbits x 16	0x142
512 Mbits x 16	0x152

In the HiSilicon reference design, the DDR capacity in the table is the maximum value supported. If the actual DDR capacity is less than the configured value, it is supported by default and you do not need to modify the table.

6.2.2 Hi3798M V100

In hi3798mdmo1b_hi3798mv100_ddr3_16bit x 2_2layers.xlsm, two 256 Mbits x 16 (totally 1 GB) DDR SDRAMs are used. Therefore, the DDRC register with the address of 0x60 is set to 0x152. See Figure 6-5.

Figure 6-5 0x60 register

12	DDRC_CFG_RNKVOL	0x60	0x152	0	write	31	0	0x0000000FF

Table 6-2 describes the mapping between the 0x60 register configurations and the DDR capacity.

Table 6-2 Mapping between the 0x60 register configurations and the DDR capacity

Capacity of a DDR	0x60 Register Configurations
128 Mbits x 16	0x142
256 Mbits x 8	0x152



In the HiSilicon reference design, the DDR capacity in the table is the maximum value supported. If the actual DDR capacity is less than the configured value, it is supported by default and you do not need to modify the table.